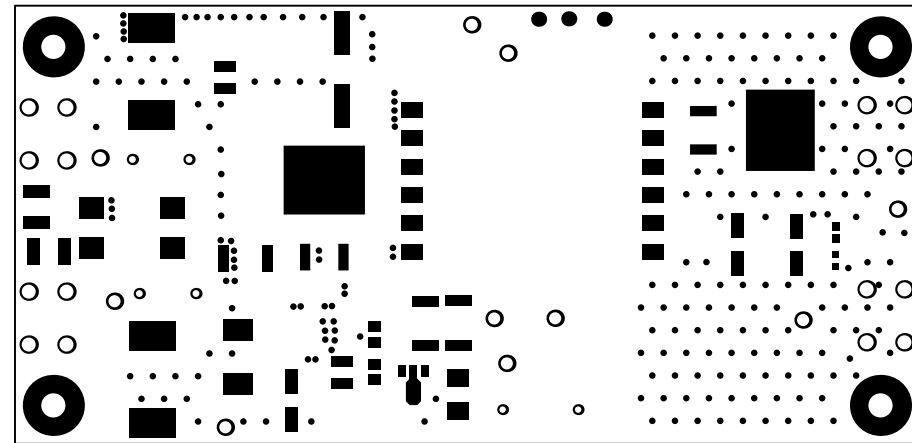
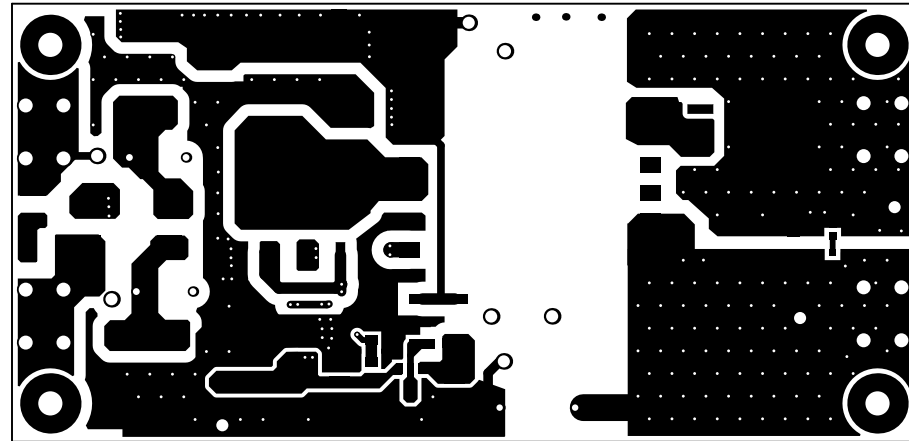


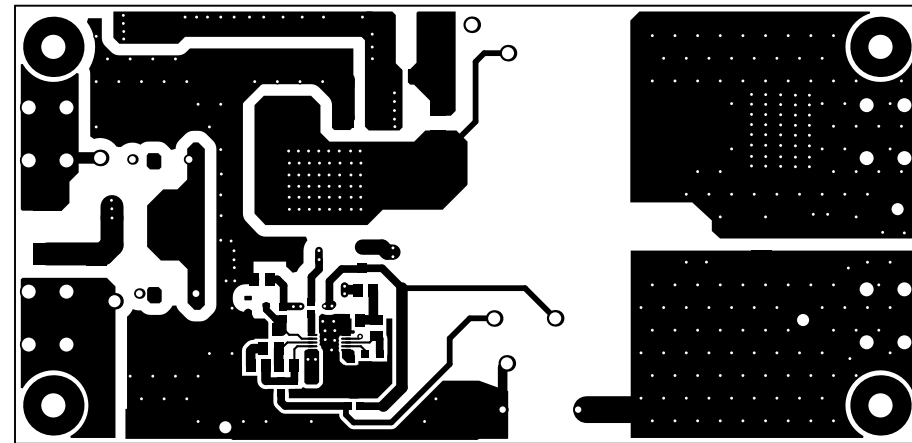
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 1344		
PLOT NAME = Top Overlay	GENERATED : 2/20/2017 1:16:05 PM	TEXAS INSTRUMENTS	



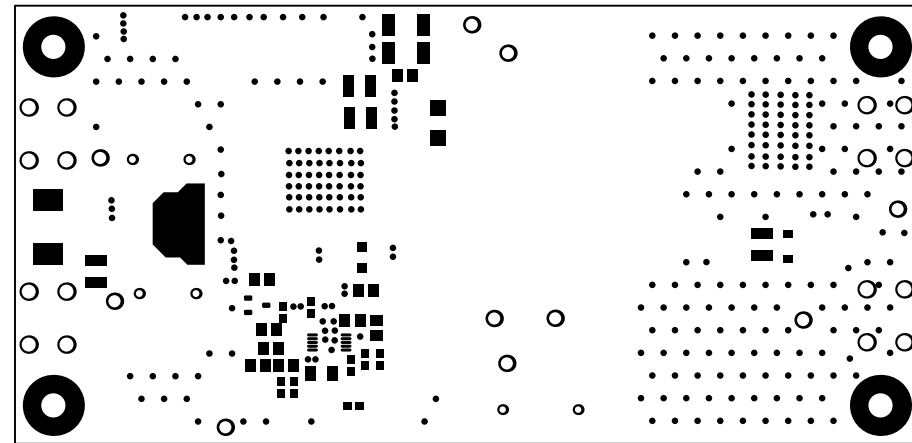
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 1344		
PLOT NAME = Top Solder Mask	GENERATED : 2/20/2017 1:16:07 PM	TEXAS INSTRUMENTS	



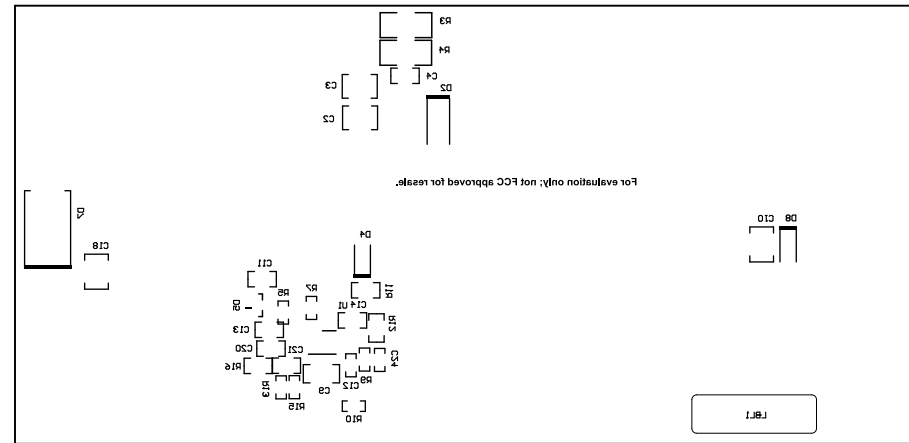
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: 1344		
PLOT NAME = Top Layer	GENERATED : 2/20/2017 1:16:09 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: 1344		
PLOT NAME = Bottom Layer	GENERATED : 2/20/2017 1:16:11 PM	TEXAS INSTRUMENTS	

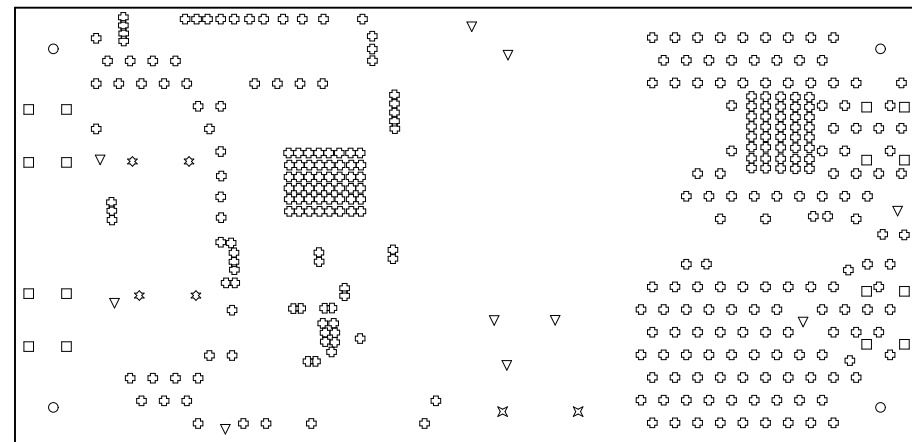


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 1344		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/20/2017 1:16:14 PM		TEXAS INSTRUMENTS

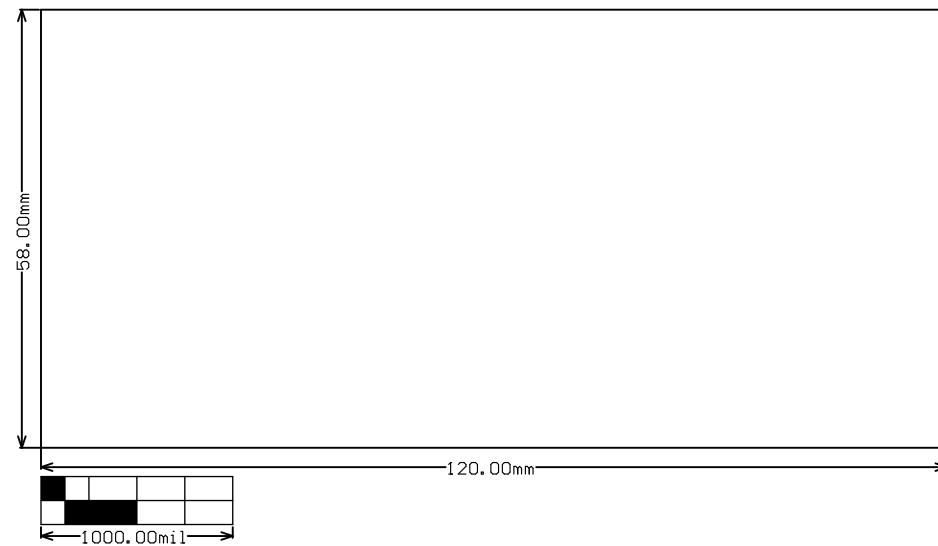


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 1344		
PLOT NAME = Bottom Overlay	GENERATED : 2/20/2017 1:16:16 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	316	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
▽	10	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
□	16	72.83mil (1.850mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	352 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 1344		
PLOT NAME = Drill Drawing	GENERATED : 2/20/2017 1:16:19 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01344	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 1344		
PLOT NAME = Board Dimensions	GENERATED : 2/20/2017 1:16:22 PM	TEXAS INSTRUMENTS	

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